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**Claim Amendments:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)
2. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the fluid medium comprises water.
3. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the mechanical waves comprise sound waves.
4. (Original) The method of claim 3, wherein the sound waves are ultrasound waves, having a frequency not less than about 20 kHz.
5. (Original) The method of claim 4, wherein the sound waves have a frequency not less than about 100 kHz.
6. (Original) The method of claim 4, wherein the sound waves have a frequency not less than about 200 kHz.
7. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the substrate is translated through the fluid medium in a reel-to-reel process.
8. (Original) The method of claim 7, wherein the substrate is translated continuously through the fluid medium while subjecting the substrate to the mechanical waves.
9. (Previously Presented) The method of claim 8, wherein the substrate is translated through the fluid medium at a rate of at least 2 inches/minute.

10. (Previously Presented) The method of claim 9, wherein the substrate is translated through the fluid medium at a rate of at least 10 inches/minute.

11. (Currently Amended) A method of forming a superconductive device, comprising:  
polishing a metal alloy substrate tape having a dimension ratio not less than  $10^2$ , the metal alloy substrate tape having first and second opposite major surfaces, at least the first opposite major surface being polycrystalline and randomly textured;  
degreasing the first opposite major surface of the substrate tape;  
cleaning the substrate, cleaning including immersing the substrate tape in a fluid medium  
and subjecting the substrate tape to mechanical waves in the fluid medium;  
~~plasma treating the surface of annealing the substrate tape;~~  
depositing a biaxially textured buffer layer by ion beam assisted deposition to overlie the substrate tape after ~~plasma treating annealing;~~ and  
depositing a superconductor layer to overlie the buffer layer.

12. (Original) The method of claim 11, wherein polishing includes reducing a surface roughness of at least one side of the substrate through a series of successive polishing operations.

13. (Original) The method of claim 11, wherein polishing is carried out by contacting the substrate with an abrasive slurry, and applying a force against the substrate to effect material removal.

14. (Currently Amended) The method of claim ~~[[1]]~~11, further comprising a step of executing a high pressure rinse prior to cleaning.

15. (Cancelled)

16. (Currently Amended) The method of claim ~~[[15]]~~11, wherein annealing is carried out at a temperature of at least 400°C.

17. (Currently Amended) The method of claim ~~[[15]]~~11, wherein annealing is carried out in a non-oxidizing environment.

18. (Original) The method of claim 17, wherein the non-oxidizing environment is a reducing environment, containing a reducing gaseous component.

19. (Original) The method of claim 17, wherein the non-oxidizing environment comprises an non-reactive gas.

20. (Currently Amended) The method of claim ~~[[15]]11~~, wherein the annealing is effective to reduce defects along a surface of the substrate.

21. (Currently Amended) The method of claim ~~[[15]]11~~, wherein the annealing is effective to remove impurities along a surface of the substrate.

22-26. (Canceled)

27. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the superconductor layer has a Tc not less than about 77K.

28. (Original) The method of claim 27, wherein the superconductor layer comprises YBCO.

29. (Currently Amended) The method of claim ~~[[1]]11~~, further comprising depositing a stabilizer layer overlying the superconductor layer.

30. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the superconductive device is a superconductive tape.

31. (Currently Amended) The method of claim ~~[[1]]11~~, wherein the superconductive device is an electric power component incorporating a superconductive tape comprising said substrate and superconductor layer.

32. (Canceled)

33. (Currently Amended) The method of claim ~~[[32]]~~11, wherein the superconductor layer overlies the first opposite major surface.

Claims 34-40 (Canceled)